

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A multi-chip module comprising:

a plurality of first semiconductor chips surface-mounted on a surface of a mounting board ~~for exchanging~~ to exchange signals with each other;

a plurality of bumps that electrically couple said plurality of first semiconductor chips with said mounting board;

a second semiconductor chip mounted back-to-back with at least one of said plurality of first semiconductor chips, said second semiconductor chip having ~~most~~ a plurality of bonding pads on a front surface thereof, a majority of said bonding pads being thereof arranged along one side ~~thereof~~ of said front surface;

a plurality of bonding wires for connecting coupling the bonding pads of said second semiconductor chip ~~and~~ with corresponding electrodes formed on said mounting board; and

,

a sealing member ~~for~~ encapsulating said plurality of first semiconductor chips, said second semiconductor chip, and ~~the~~ said bonding ~~wire~~ wires, on said mounting board.

2. (Currently Amended) A multi-chip module according to claim 1,

wherein said plurality of first semiconductor chips include a microcomputer chip, a random access memory chip, and a signal processing ~~device for processing~~ chip adapted to process signals for specific applications, respectively; and

wherein said second semiconductor chip is a nonvolatile memory chip.

3. (Currently Amended) A multi-chip module according to claim 2,

wherein said microcomputer chip is coupled to one of ~~and~~ said random access memory ~~[[or]]~~ chip and said signal processing chip ~~device for processing the signal for specified applications which is connected to said microcomputer are interconnected by wiring of said formed on the mounting board by imposition;~~ and

wherein said microcomputer chip includes an exclusive interface corresponding to said nonvolatile memory chip,

said microcomputer chip and said nonvolatile memory chip being interconnected through said bonding ~~wire~~ wires.

4. (Currently Amended) A multi-chip module according to claim 3,

wherein said at least one of said plurality of first semiconductor chips mounted back-to-back with said nonvolatile memory chip includes at least ~~is mounted back-to-back with said microcomputer chip first semiconductor chips including said microcomputer.~~

5. (Currently Amended) A multi-chip module according to claim 4,

wherein said at least one of said plurality of first semiconductor chips mounted back-to-back with said nonvolatile memory chip further includes ~~include said microcomputer and~~ said random access memory chip; and

wherein ~~the~~ a long side of ~~the semiconductor chip constituting~~ said random access memory chip and ~~the~~ a long side of ~~the semiconductor chip constituting~~ said nonvolatile memory chip are arranged orthogonally with respect to each other.